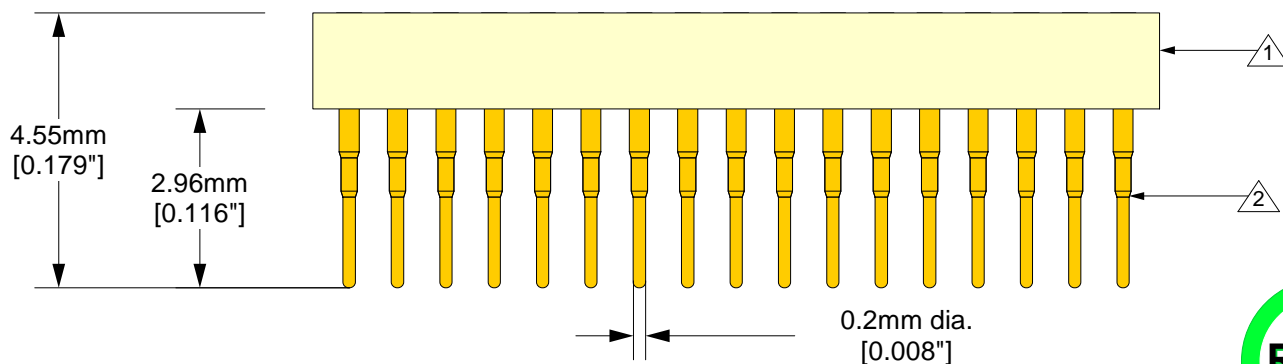


Side View




1 Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"]
FR4/G10 or equivalent high temp material. non clad

2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).

Description: Giga-snaP BGA SMT Land Socket

136 position BGA surface mount land pattern to terminal pins (0.8mm centers, 17x8 array)

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

LS-BGA136C-61 Drawing		Status: Released	Scale: 8:1	Rev: C
 <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: J. Glab		Date: 2/15/07	
	File: LS-BGA136C-61 Dwg.mcd		Modified: 01/18/13, Dh	